



IRP3216N18-D0

SMD Type 940nm Infrared Emitter

Features

- Small double-end package
- Viewing Angle = $\pm 15^\circ$
- High radiant intensity
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

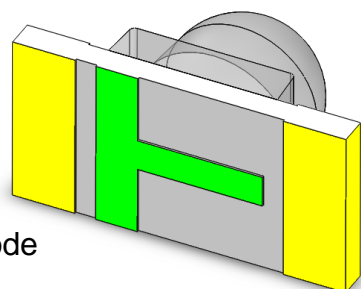
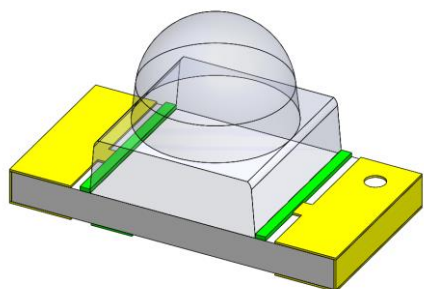
Applications

- Infrared sensor

Description

The IRP3216N18-D0 is a GaAlAs infrared LED housed in a miniature SMD package. The device has a peak wavelength of 940nm LED spectrally matched with phototransistor or photodiode.

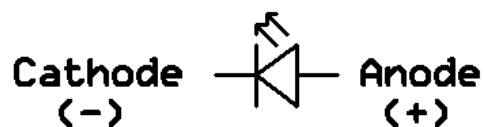
Package Outline



Anode

Cathode

Schematic





Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
I _F	Continuous Forward Current	70	mA	
I _{FP}	Peak Forward Current	0.7	A	1
V _R	Reverse Voltage	5	V	
T _{opr}	Operating Temperature	-40 ~ +85	°C	
T _{stg}	Storage Temperature	-40 ~ +100	°C	
T _{sol}	Soldering Temperature	260	°C	2
P _D	Power Dissipation at(or below) 25°C Free Air Temperature	119	mW	
R _{THJA}	Junction to Ambient Thermal Resistance	540	°C/W	

Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

Optical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I _e	Radiant Intensity	I _F =20mA	3.0	5.2	8.0	mW/sr	3
		I _F =70mA	-	18	-		
λ _p	Peak Wavelength	I _F =20mA	-	940	-	nm	
Δλ	Spectral Bandwidth	I _F =20mA	-	50	-	nm	
θ1/2	Angle of Half Intensity	I _F =20mA	-	±15	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V _F	Forward Voltage	I _F =20mA	1.1	1.20	1.50	V	
		I _F =70mA	1.2	1.34	1.70		
I _R	Reverse Current	V _R =5V	-	-	10	μA	

Notes:

1 : I_{FP} Conditions--Pulse Width ≤ 100μs and Duty ≤ 1%.

2 : Soldering time ≤ 5 seconds.

3 : I_e Bin Rank :

Bin Code	Fb	G
Min	3.0	4.0
Max	5.0	8.0



Typical Characteristic Curves

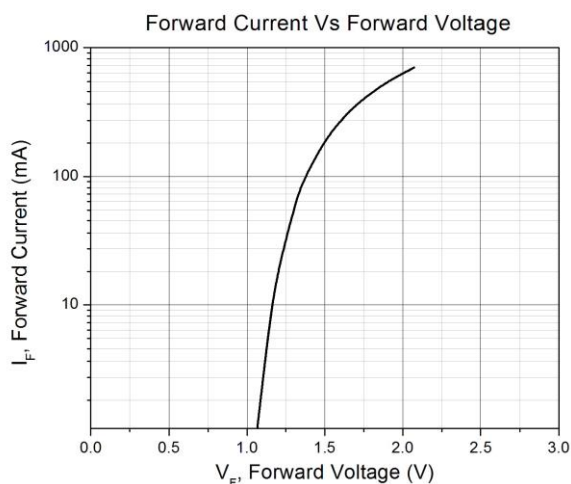


Figure 1

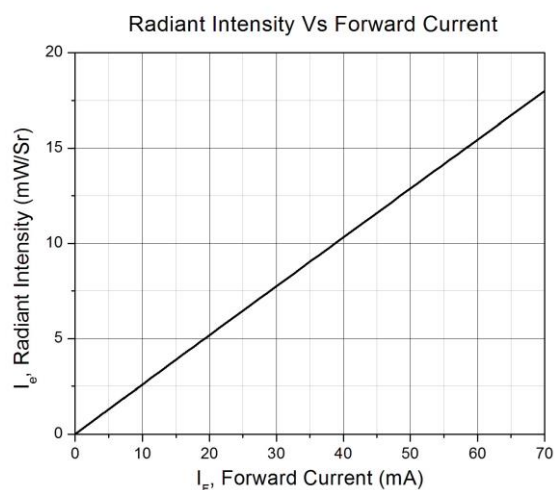


Figure 2

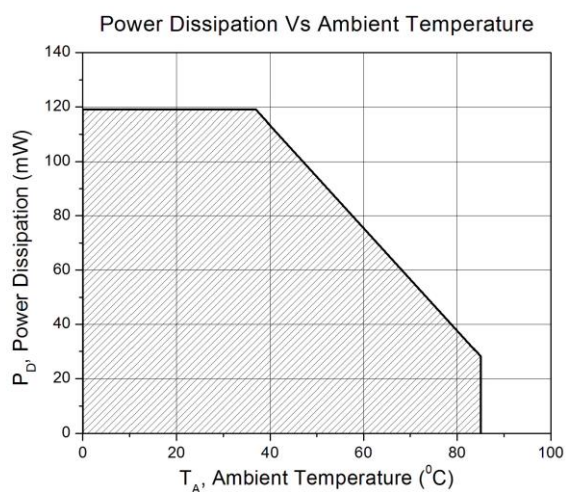


Figure 3

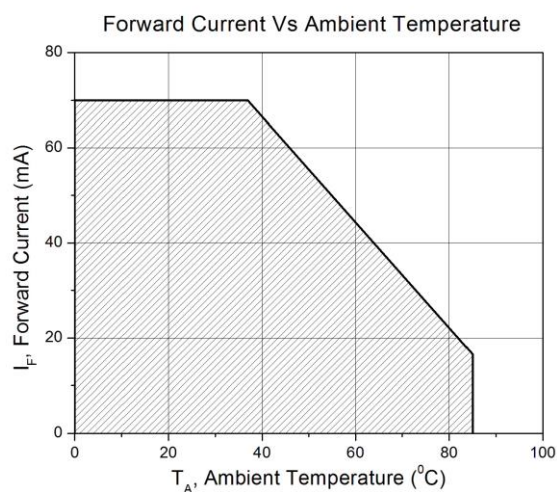


Figure 4

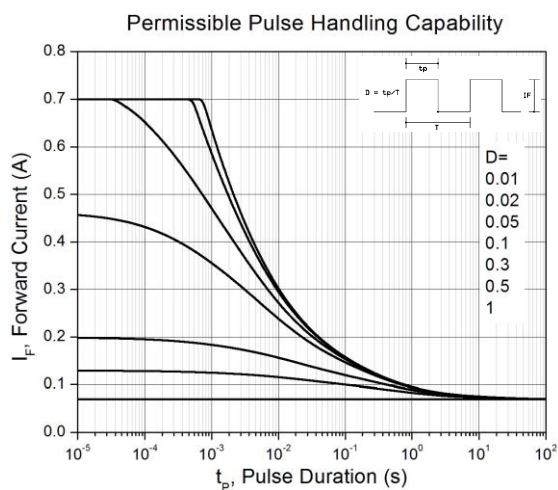


Figure 5

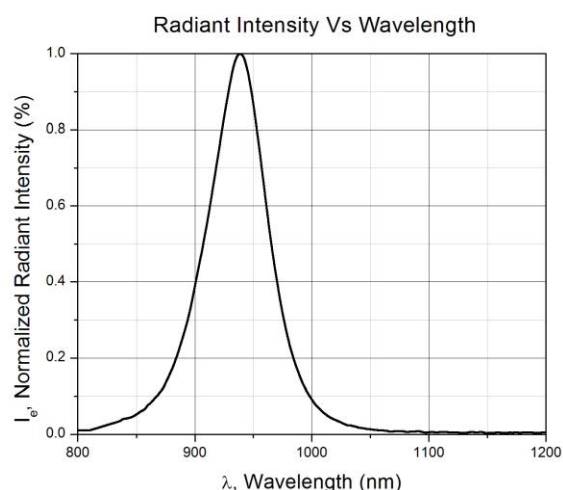
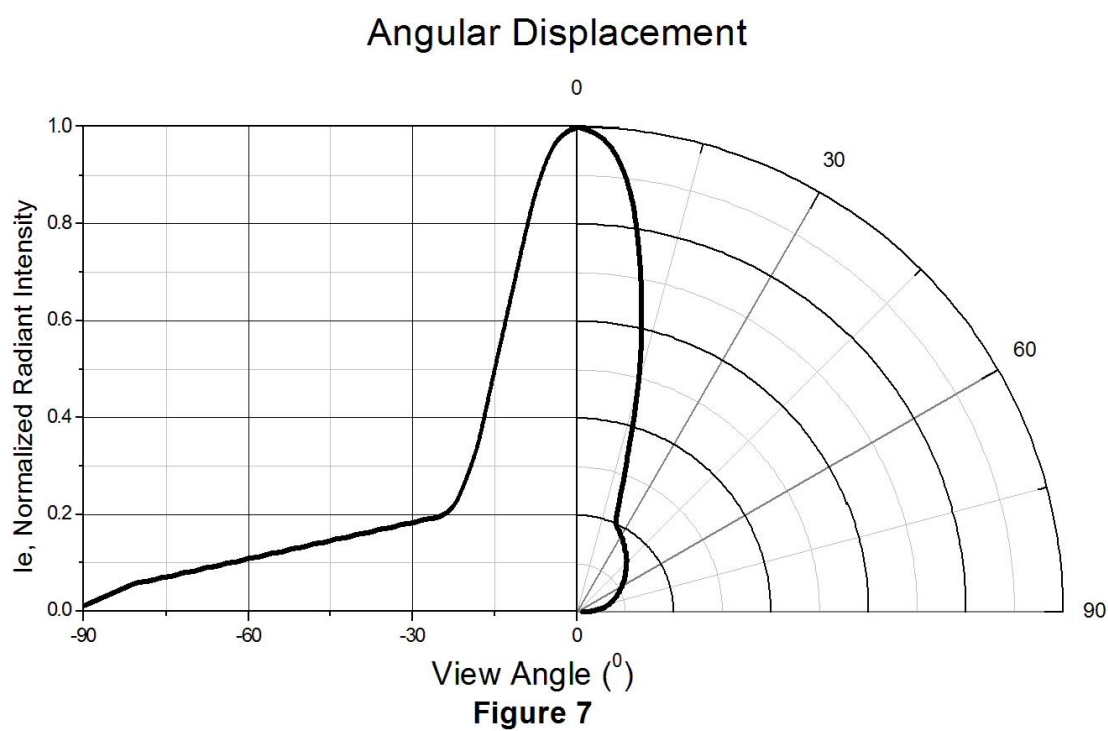


Figure 6

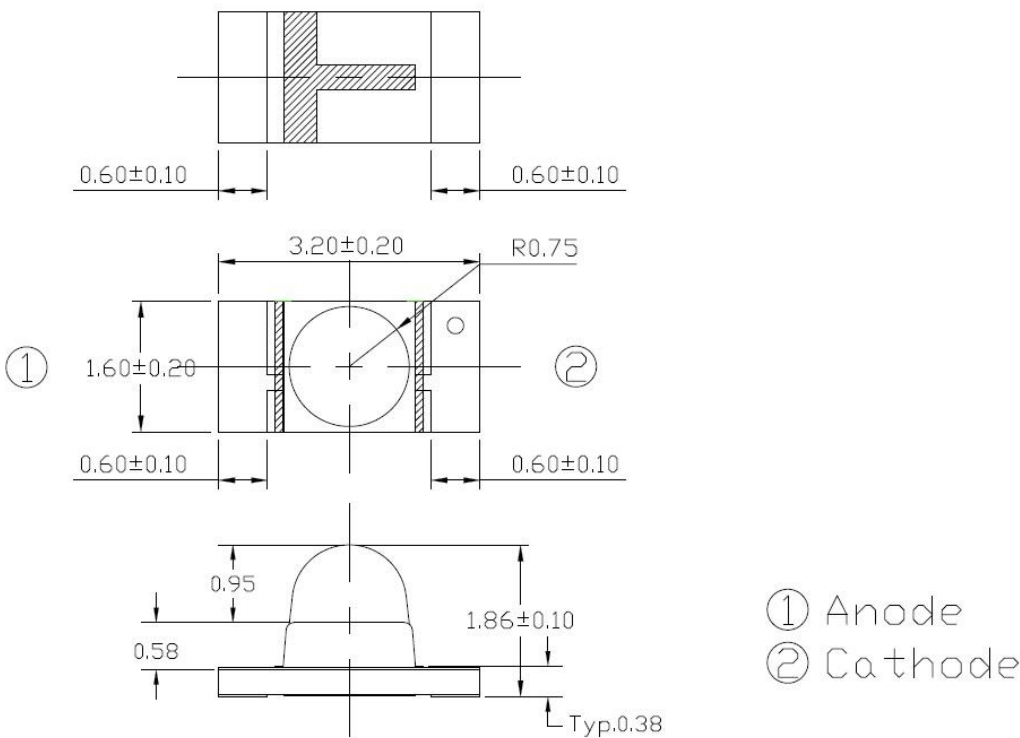


Typical Characteristic Curves

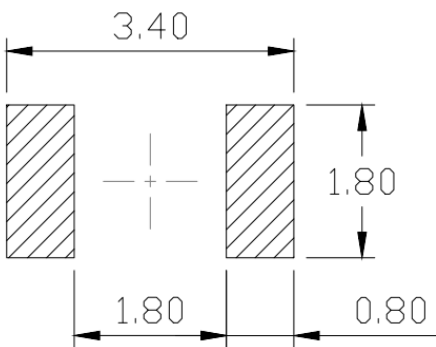




Package Dimension *All dimensions are in mm, unless otherwise stated*



Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*



Ordering Information

Part Number	Description	Quantity
IRP3216N18-D0	Tape & Reel	2000 pcs

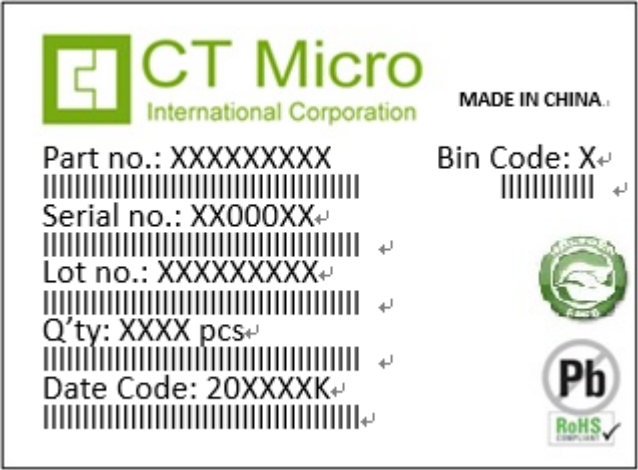


Reel Dimension *All dimensions are in mm, unless otherwise stated*





Label Form Specification



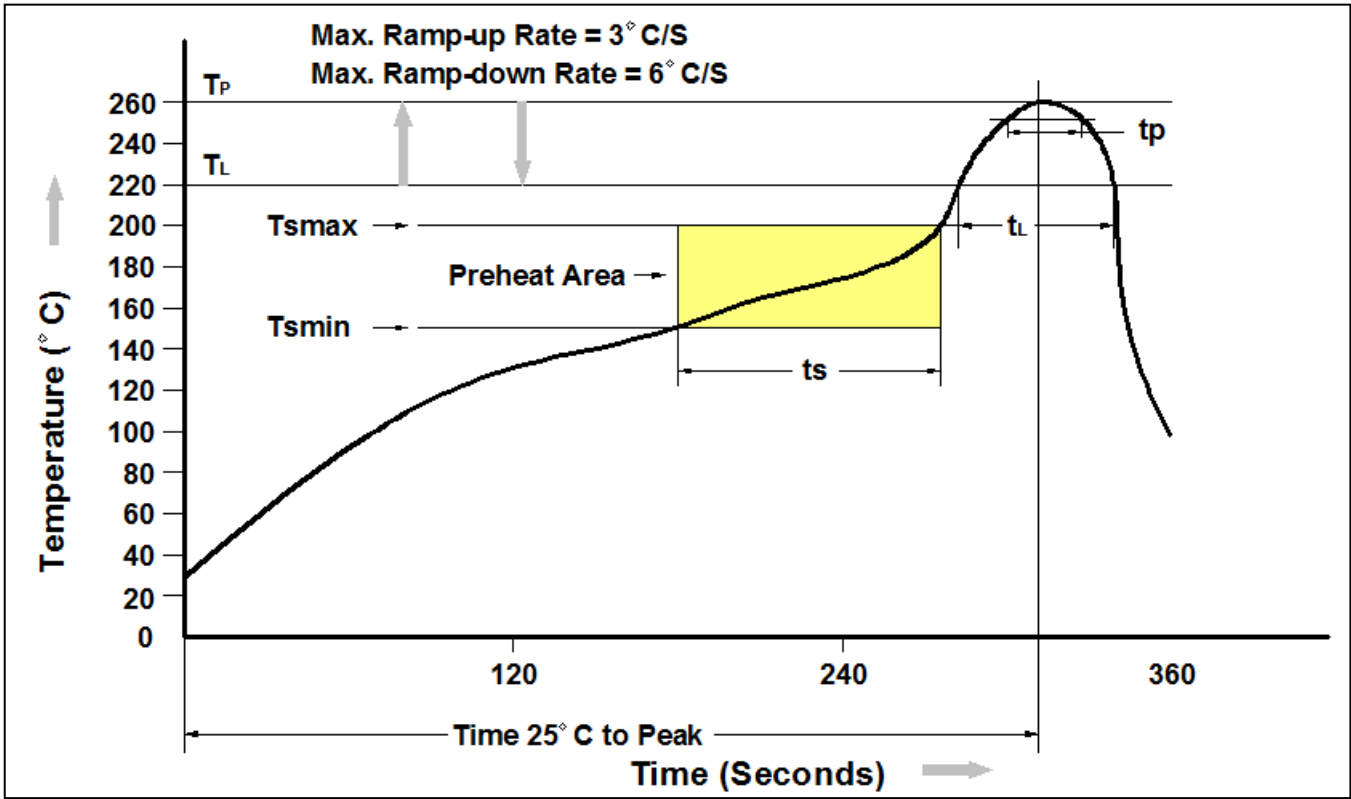
Part no: CTM Production Number
Serial no: Production Number
Lot no: Lot number
Q'ty: Packing Quantity
Date Code: Manufacture Date
Bin Code: 1e Ranks
MADE IN CHINA: Production Place

Storage Condition

- 1. Do not open moisture proof bag before the products are ready to use.
- 2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening.
Shelf life of non-opened bag is 12 months after the bag sealing date.
- 3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
- 4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (tl to tp)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tl) Maintained Above (TL)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (tp) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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